

**Notification# 20190820009**  
**Datasheet for TPS1H000-Q1**  
**Information Only**

**Date:** August 29, 2019

Dear Customer:

This is an information-only announcement of a change to the datasheet for a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN team ([PCN\\_ww\\_admin\\_team@list.ti.com](mailto:PCN_ww_admin_team@list.ti.com)).

Sincerely,

PCN Team  
SC Business Services

## Information Only Attachments

### Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

<b>DEVICE</b>	<b>CUSTOMER PART NUMBER</b>
TPS1H000AQDGNRQ1	null

Technical details of this Product Change follow on the next page(s).

<b>PCN Number:</b>	20190820009	<b>PCN Date:</b>	Aug. 29, 2019
<b>Title:</b>	Datasheet for TPS1H000-Q1		
<b>Customer Contact:</b>	PCN Manager	<b>Dept:</b>	Quality Services
<b>Change Type:</b>			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

### Notification Details

#### Description of Change:

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.



TPS1H000-Q1

SLVSD06C – AUGUST 2017 – REVISED JUNE 2019

#### Changes from Revision B (March 2018) to Revision C

Page

- Changed IN is high and DIAG\_EN is high to IN is low and DIAG\_EN is low in the *Standby Mode* section ..... 21

The datasheet number will be changing.

Device Family	Change From:	Change To:
TPS1H000-Q1	SLVSD06B	SLVSD06C

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/TPS1H000-Q1>

#### Reason for Change:

To accurately reflect device characteristics.

#### Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

#### Changes to product identification resulting from this PCN:

None.

#### Product Affected:

TPS1H000AQDGNRQ1			
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For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	<a href="mailto:PCNAmericasContact@list.ti.com">PCNAmericasContact@list.ti.com</a>
Europe	<a href="mailto:PCNEuropeContact@list.ti.com">PCNEuropeContact@list.ti.com</a>
Asia Pacific	<a href="mailto:PCNAsiaContact@list.ti.com">PCNAsiaContact@list.ti.com</a>
WW PCN Team	<a href="mailto:PCN_ww_admin_team@list.ti.com">PCN_ww_admin_team@list.ti.com</a>

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